HD74BC244A

Octal Buffers/Line Drivers With 3 State Outputs

REJ03D0281–0300Z
(Previous ADE-205-007A (Z))
Rev.3.00
Jul.16.2004

Description

The HD74BC244A provides high drivability and operation equal to or better than high speed bipolar standard logic IC by using Bi-CMOS process. The device features low power dissipation that is about 1/5 of high speed bipolar logic IC, when the frequency is 10 MHz. The device has eight inverter drivers with three state outputs in a 20 pin package. This device is a non inverting buffer and has two active low enables ($1\overline{G}$ and $2\overline{G}$). Each enable independently controls 4 buffers.

Features

- Input/Output are at high impedance state when power supply is off.
- Built in input pull up circuit can make input pins be open, when not used.
- TTL level input
- Wide operating temperature range
  Ta = –40 to + 85°C
- Ordering Information

Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74BC244AP	DILP-20 pin	DP-20N, -20NEV	P	—
HD74BC244AFPEL	SOP-20 pin (JEITA)	FP-20DAV	FP	EL (2,000 pcs/reel)
HD74BC244ATELL	TSSOP-20 pin	TTP-20DAV	T	ELL (2,000 pcs/reel)

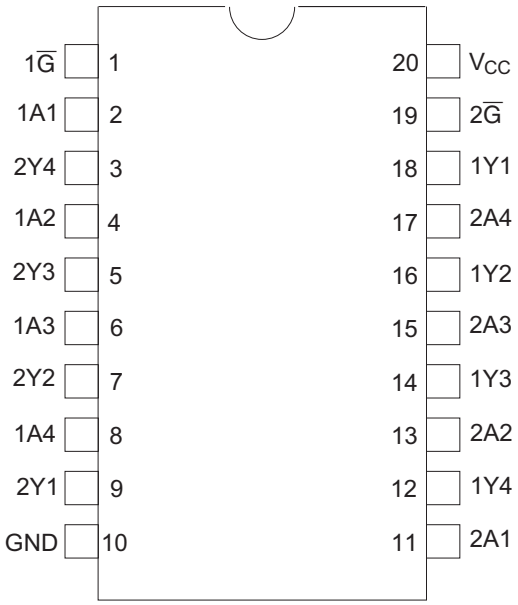
Note: Please consults the sales office for the above package availability.

Function Table

Inputs		Output Y
$\overline{G}$	A	
H	X	Z
L	H	H
L	L	L

H : High level
L : Low level
X : Immaterial
Z : High impedance

Pin Arrangement



(Top view)

Absolute Maximum Ratings

Item	Symbol	Rating	Unit
Supply voltage	V_{CC}	–0.5 to +7.0	V
Input diode current	I_{IK}	±30	mA
Input voltage	V_{IN}	–0.5 to +7.5	V
Output voltage	V_{OUT}	–0.5 to +7.5	V
Off state output voltage	$V_{OUT(off)}$	–0.5 to +5.5	V
Storage temperature	Tstg	–65 to +150	°C

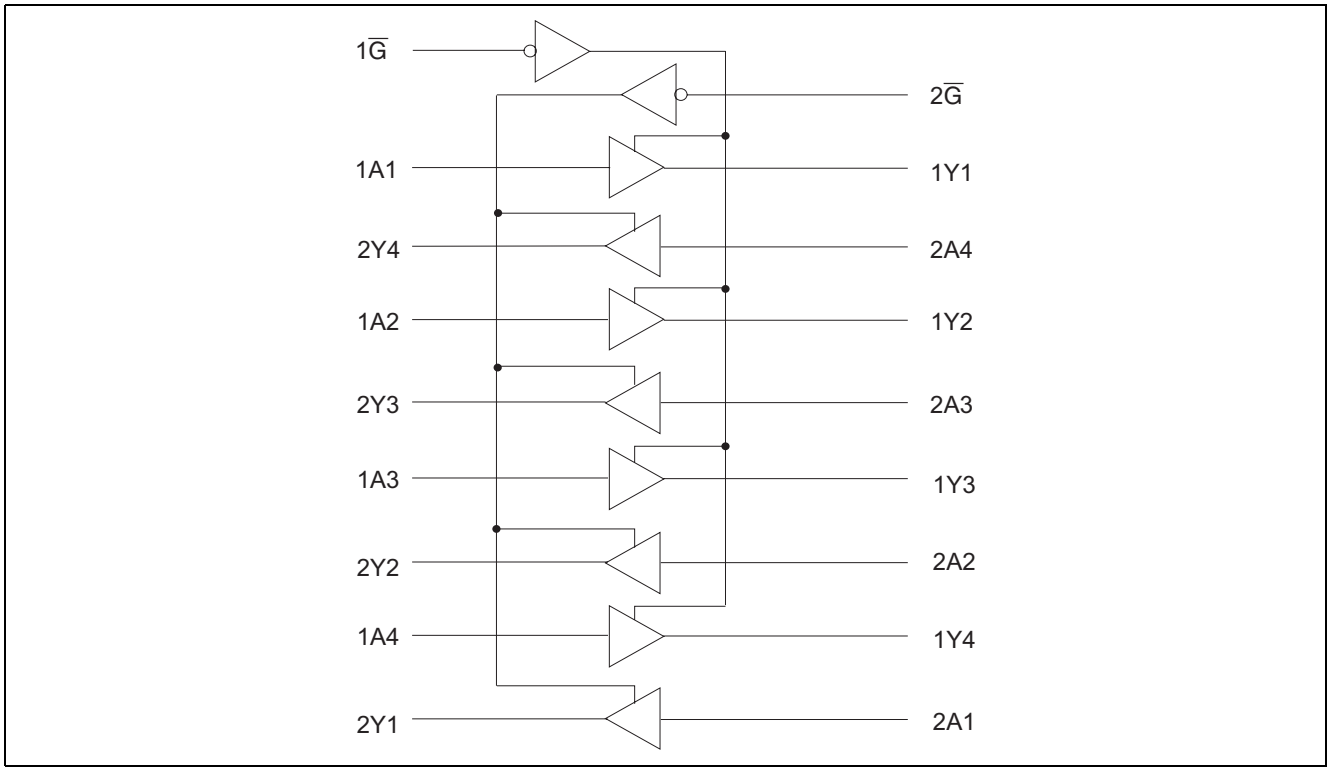
Note: 1. The absolute maximum ratings are values which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.5	5.0	5.5	V
Input voltage	V_{IN}	0	—	V_{CC}	V
Output voltage	V_{OUT}	0	—	V_{CC}	V
Operating temperature	Topr	–40	—	85	°C
Input rise/fall time*[1]	t_r, t_f	0	—	8	ns/V

Note: 1. This item guarantees maximum limit when one input switches.
Waveform: Refer to test circuit of switching characteristics.

Logic Diagram



Electrical Characteristics (Ta = –40°C to +85°C)

Item	Symbol	V_{CC}(V)	Min	Max	Unit	Test Conditions
Input voltage	V_{IH}		2.0	—	V	
	V_{IL}		—	0.8	V	
Output voltage	V_{OH}	4.5	2.4	—	V	I_{OH} = –3 mA
		4.5	2.0	—	V	I_{OH} = –15 mA
	V_{OL}	4.5	—	0.5	V	I_{OL} = 48 mA
		4.5	—	0.55	V	I_{OL} = 64 mA
Input diode voltage	V_{IK}	4.5	—	–1.2	V	I_{IN} = –18 mA
Input current	I_I	5.5	—	–250	µA	V_{IN} = 0 V
		5.5	—	1.0	µA	V_{IN} = 5.5 V
		5.5	—	100	µA	V_{IN} = 7.0 V
Short circuit output current*1	I_{OS}	5.5	–100	–225	mA	V_{IN} = 0 or 5.5 V
Off state output current	I_{OZH}	5.5	—	50	µA	V_O = 2.7 V
	I_{OZL}	5.5	—	–50	µA	V_O = 0.5 V
Supply current	I_{CCL}	5.5	—	29.5	mA	V_{IN} = 0 or 5.5 V All outputs is “L”
	I_{CCH}	5.5	—	0.5	mA	V_{IN} = 0 or 5.5 V All outputs is “H”
	I_{CCZ}	5.5	—	2.5	mA	V_{IN} = 0 or 5.5 V All outputs is “Z”
	I_{CCT}*2	5.5	—	1.5	mA	V_{IN} = 3.4 or 0.5 V

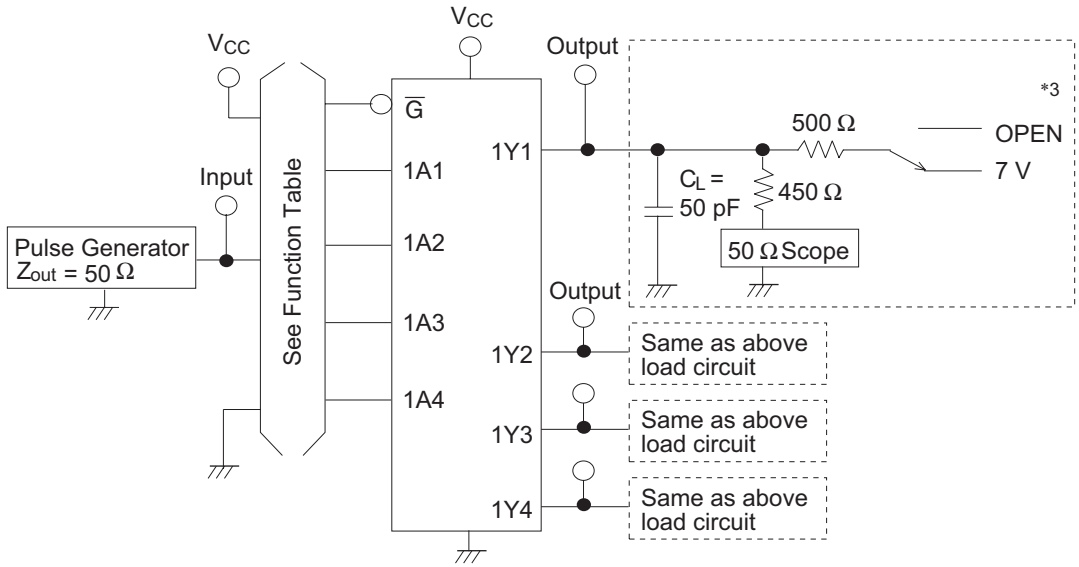
Notes : 1. Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

2. When input by the TTL level, it shows I_{CC} increase at per one input pin.

Switching Test Method (C_L = 50 pF)

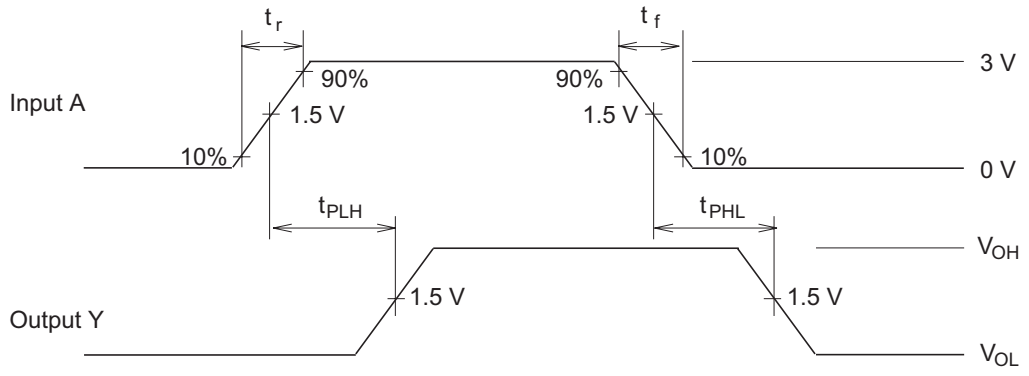
Item	Symbol	Ta = 25°C V_{CC} = 5.0 V		Ta = –40 to 85°C V_{CC} = 5.0 V ±10%		Unit	Test Conditions
		Min	Max	Min	Max		
Propagation delay time	t_{PLH}	3.0	6.0	3.0	7.0	ns	See under figure
	t_{PHL}	3.0	6.0	3.0	7.0		
Output enable time	t_{ZH}	3.0	8.0	3.0	10.0	ns	
	t_{ZL}	3.0	8.0	3.0	10.0		
Output disable time	t_{HZ}	3.0	7.0	3.0	9.0	ns	
	t_{LZ}	3.0	7.0	3.0	9.0		
Input capacitanse	C_{IN}	3.0(Typ)		—		pF	V_{IN} = V_{CC} or GND
Output capacitance	C_O	15.0(Typ)		—		pF	V_O = V_{CC} or GND

Test Circuit



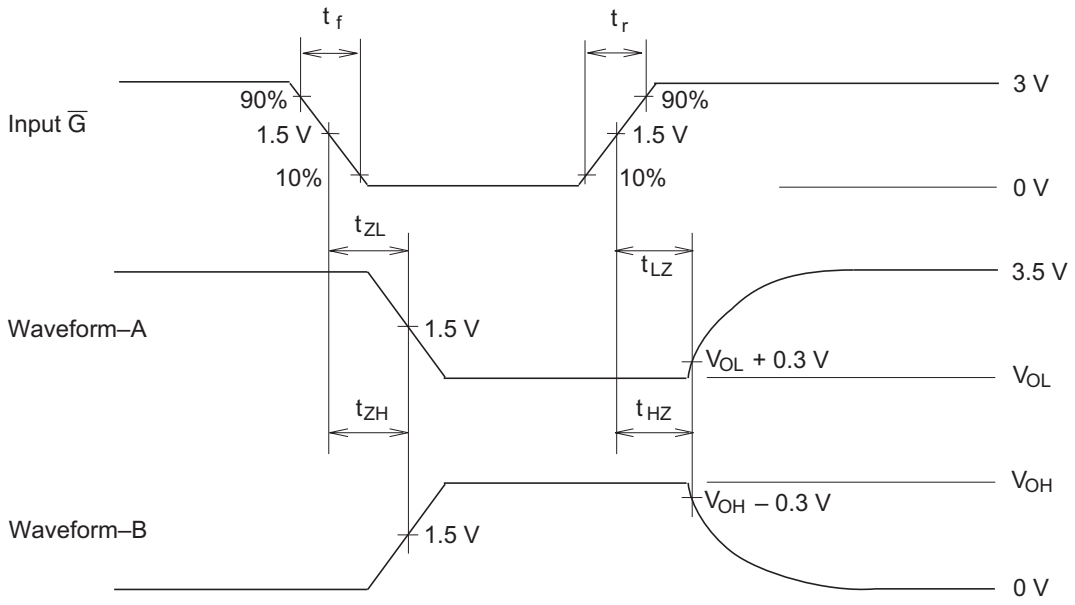
Notes:
1. C_L includes probe and jig capacitance.
2. $2\overline{G}$, 2A1-2A4 to 2Y1-2Y4 are identical to above load circuit.
3. Open: t_{PLH}, t_{PHL}, t_{ZH}, t_{HZ}
   7 V: t_{ZL}, t_{LZ}

Waveforms-1



Notes: 1. t_r = 2.5 ns, t_f = 2.5 ns
2. Input waveform: PRR =1 MHz, duty cycle 50%

Waveforms-2

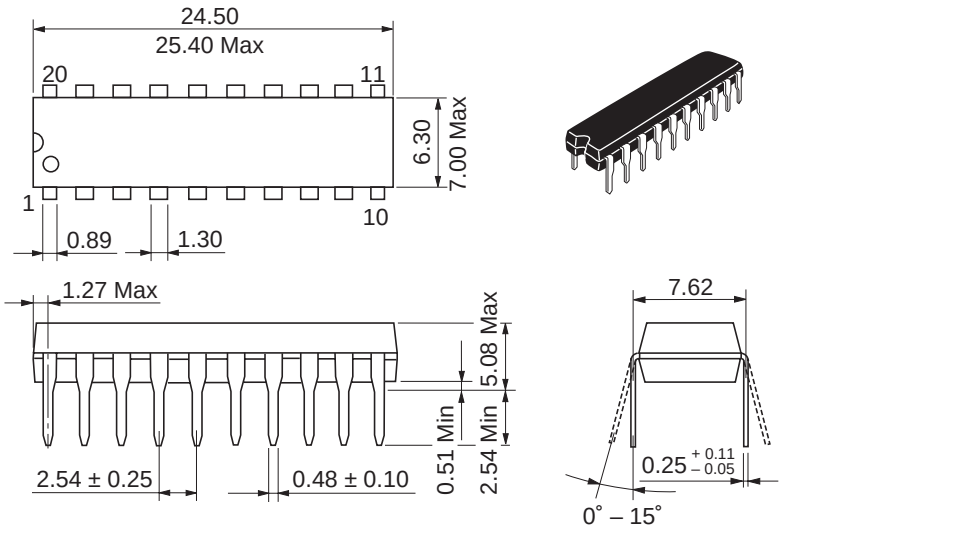


Notes: 1. t_r = 2.5 ns, t_f = 2.5 ns
2. Input waveform: PRR = 1 MHz, duty cycle 50%
3. Waveform-A shows input conditions such that the output is “L” level when enable by the output control.
4. Waveform-B shows input conditions such that the output is “H” level when enable by the output control.

Package Dimensions

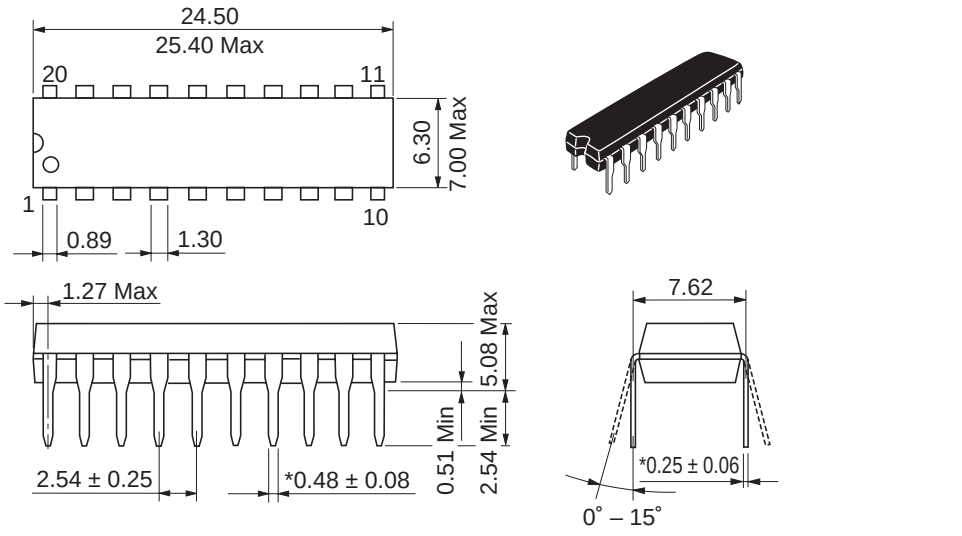
As of January, 2003

Unit: mm



Package Code	DP-20N
JEDEC	—
JEITA	Conforms
Mass (reference value)	1.26 g

Unit: mm

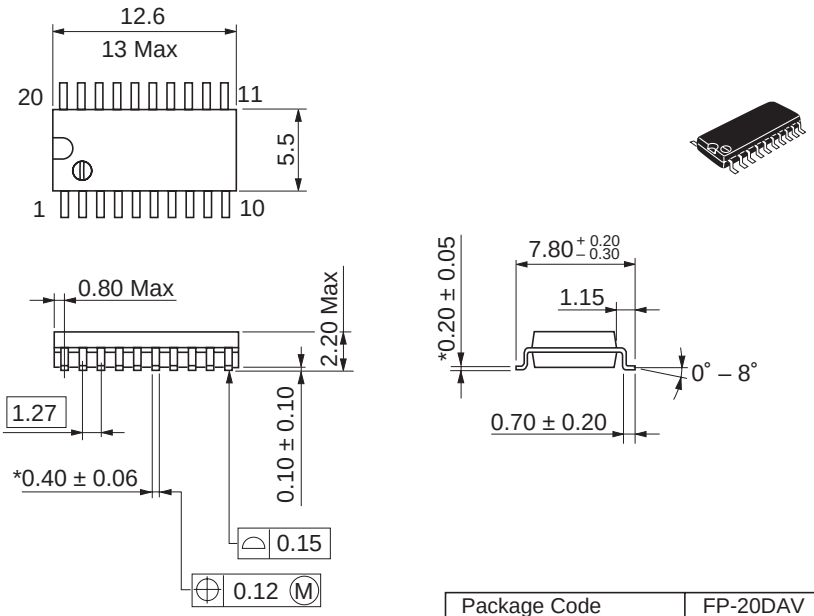


*NI/Pd/AU Plating

Package Code	DP-20NEV
JEDEC	—
JEITA	Conforms
Mass (reference value)	1.26 g

As of January, 2003

Unit: mm

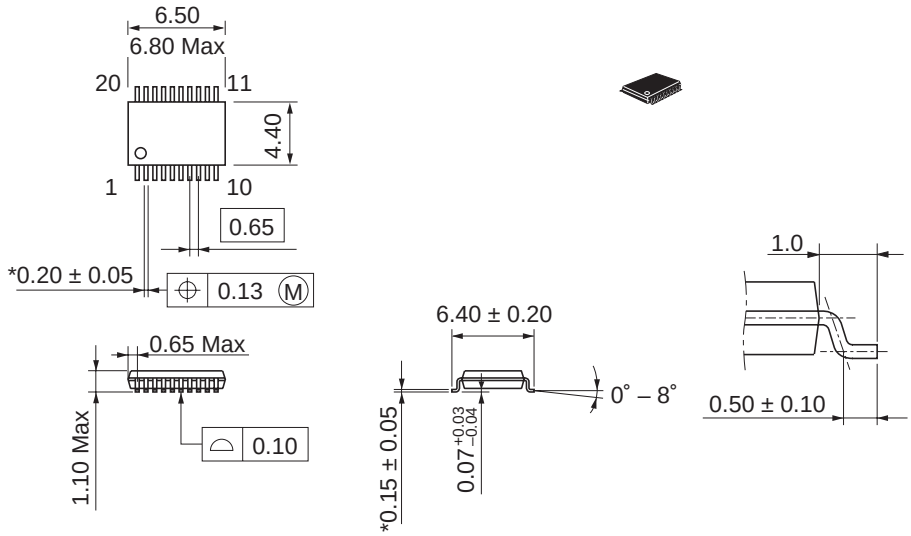


*Ni/Pd/Au plating

Package Code	FP-20DAV
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.31 g

As of January, 2003

Unit: mm



*Ni/Pd/Au plating

Package Code	TTP-20DAV
JEDEC	—
JEITA	—
Mass (reference value)	0.07 g

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